

Features

- High isolation 3750 VRMS
- High B_{VCEO} = 350V
- Patented coplanar structure DMC-Isolator®
- DC input with Darlington output
- Operating Temperature range 55 °C to 110 °C
- External Creepage ≥ 5.0mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 5.0mm
- RoHS and REACH Compliance
- Halogen Free Compliance
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5(VDE0884-5)
 - ✓ CQC GB4943.1, GB8898 (14001105803)
 - ✓ IEC62368 (FI/41119)

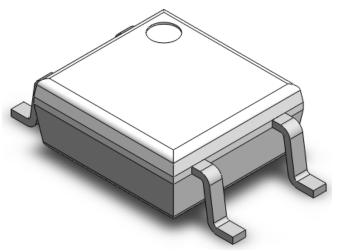
Description

The CT452 series consists of a High B_Vceo Photodarlington optically coupled to an Infrared-emitting diode in a 4-lead Mini-Flat DMC-Isolator® package with bending option.

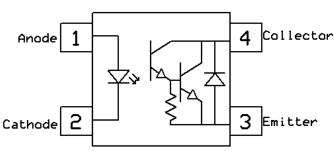
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic







Absolute Maximum Ratings $T_A = 25$ °C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	V _{RMS}	
Topr	Operating temperature	-55 ~ +110	°C	
Tstg	Storage temperature	-55 ~ +125	°C	
Tsol	Soldering temperature (For 10 seconds)	260	°C	
Ртот	Total power dissipation	170	mW	
Emitter		·	•	
I _F	Forward current	60	mA	
I _F (TRANS)	Peak transient current (≤1µs P.W,300pps)	1	А	
V _R	Reverse voltage	6	V	
Pc	Power dissipation	150	mW	
Detector	•			
P _D	Power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	350	V	
Bveco	Emitter-Collector Breakdown Voltage	0.1	V	
Ic	Collector Current	150	mA	



Electrical Characteristics $T_A = 25^{\circ}C$, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	1.24	1.4	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
C _{IN}	Input Capacitance	f= 1MHz	-	15	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
B _{VCEO}	Collector-Emitter Breakdown	Ic= 100μA	350	-	-	V	
Bveco	Emitter-Collector Breakdown	I _E = 100μA	0.1		-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 200V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

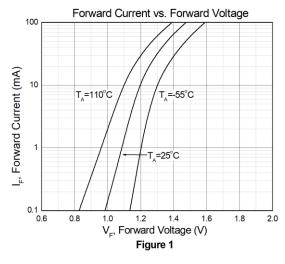
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
CTR	Current Transfer Ratio	I _F = 1mA, V _{CE} = 2V	1000		15000	%	
VCE(SAT)	Collector-Emitter Saturation Voltage	I _F = 20mA, I _C = 100mA	-	ı	1.2	٧	
Rıo	Isolation Resistance	Vio= 500VDC	5x10 ¹⁰	-	-	Ω	
C _{IO}	Isolation Capacitance	f= 1MHz	-	0.6	-	pF	

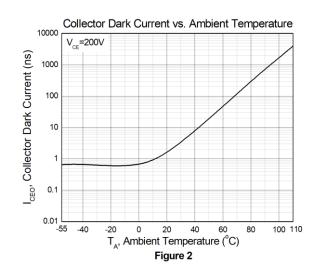
Switching Characteristics

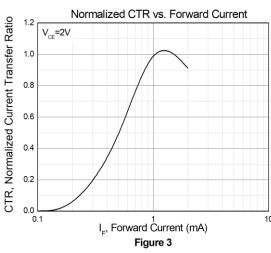
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
t _r	Rise Time	Ic=20mA, VcE= 2V,	-	100	250	0	
t f	Fall Time	R _L = 100Ω	-	20	95	μS	

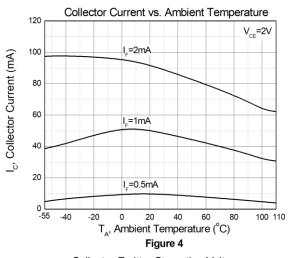


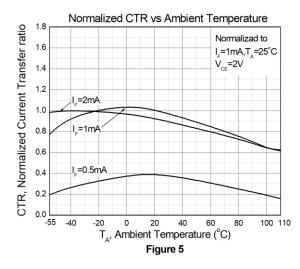
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

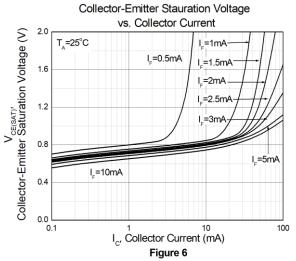


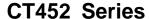






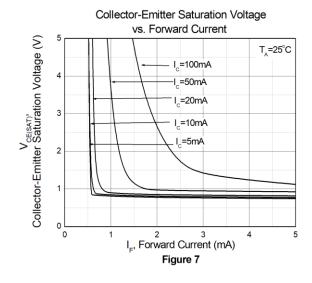


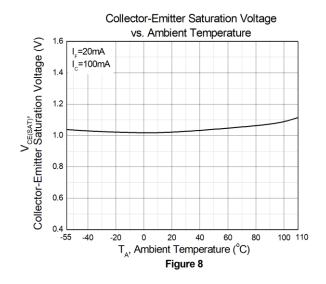


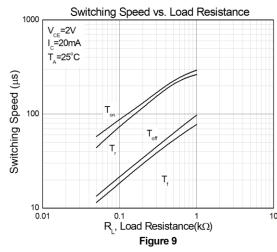


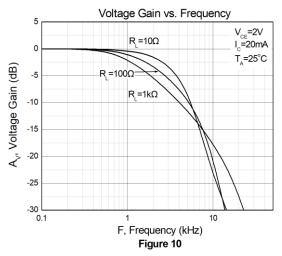


Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified











Test Circuit

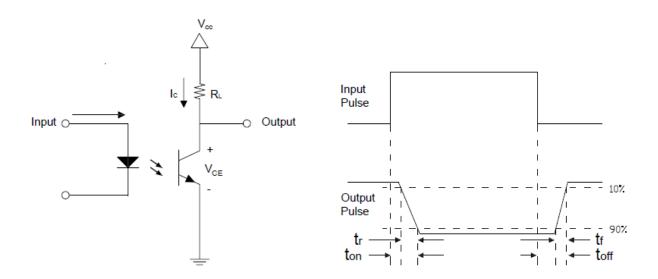
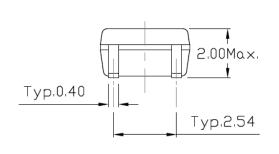
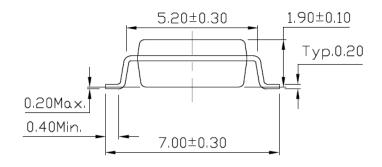


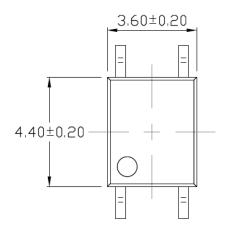
Figure 11: Switching Time Test Circuits

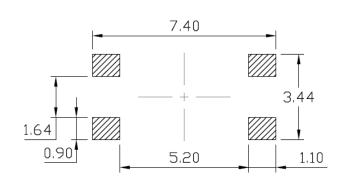


Package Dimension Dimensions in mm unless otherwise stated

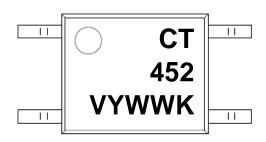








Marking Information



Note:

CT : Denotes "CT Micro"

452 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code



Ordering Information

CT452 (V)(Z)

CT = Denotes "CT Micro"

452 = Part Number

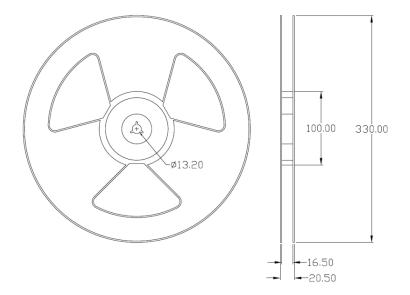
V = VDE Safety Mark Option (Blank or V)

Z = Tape and Reel Option (T1 or T2)

Option	Option Description	
T1	Surface Mount Lead Forming – With Option 1 Taping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000 Units/Reel

Reel Dimension All dimensions are in mm, unless otherwise stated

Option T1/T2

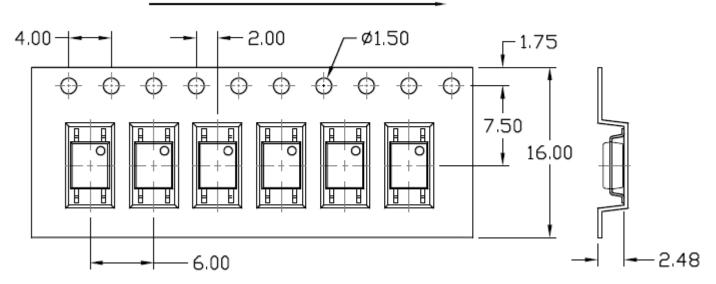




Carrier Tape Specifications Dimensions in mm unless otherwise stated

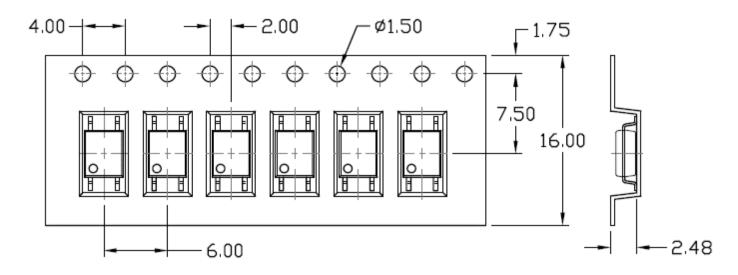
Option T1

Input Direction



Option T2

Input Direction





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

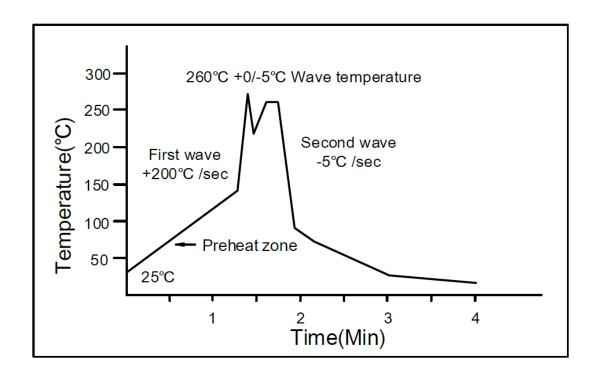
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

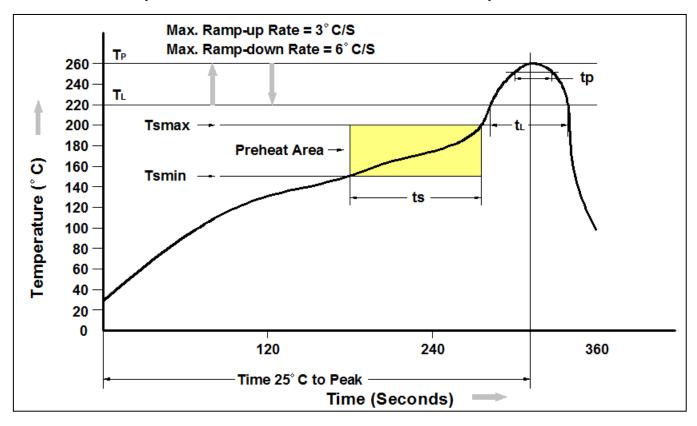
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T∟)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



CT452 Series

DC Input 4-Pin Mini-Flat DMC-Isolator[®] High B_{VCEO} Photo Darlington Optocoupler

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